









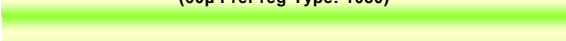














Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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10	191	FR4	35	L20.35	P10_06	S1
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columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

10_191_FR4_35_L20.35_p10_06_s1

Layers	in μ	Material	Build-Up	Assembly			
Layer-1	35 μ	Copper		} A1			
	100 μ	Prepreg			(100 μ PrePreg-Type: 2125)		
	100 μ	Prepreg					
Layer-2	35 μ	Copper			} A2		
	200 μ	L-FR4					
Layer-3	35 μ	Copper				} A3	
	60 μ	Prepreg					(60 μ PrePreg-Type: 1080)
	60 μ	Prepreg					
Layer-4	35 μ	Copper					} A4
	200 μ	L-FR4					
Layer-5	35 μ	Copper		} B			
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-6	35 μ	Copper			} B		
	200 μ	L-FR4					
Layer-7	35 μ	Copper				} B	
	60 μ	Prepreg					
	60 μ	Prepreg					
Layer-8	35 μ	Copper					} B
	200 μ	L-FR4					
Layer-9	35 μ	Copper		} B			
	100 μ	Prepreg					
	100 μ	Prepreg					
Layer-99	35 μ	Copper			} B		
	100 μ	Prepreg					
Layer-99	35 μ	Copper				} B	
	100 μ	Prepreg					
Layer-99	35 μ	Copper					} B
	100 μ	Prepreg					
Layer-99	35 μ	Copper		} B			
	100 μ	Prepreg					

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